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**INNOVATION AND COMMERCIALISATION MANAGEMENT CENTRE**

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**INVENTION DISCLOSURE FORM [IDF]**

**FOR PATENT/ UTILITY INNOVATION/ PLANT VARIETY PROTECTION**

***(Please complete this form with IP1.)***

**PART A (This Section MUST BE COMPLETED)**

|  |  |  |  |
| --- | --- | --- | --- |
| **Name of Researcher** | : |  |  |
|  **IC/ Passport No.** | : |  | **Staff ID :** |
| **Co-researcher(s) (if any)***(Please include IC/Passport No. & email address and give attachment if necessary. )* |  | 1. |  |
|  | 2. |  |
| **Faculty/Institution** | : |   |  |
| **Tel. No.** | : |  **H/P No. :**  |  **Fax No. :** |
| **E-mail** | : |  |  |
| **Duration of Research** | : | **Start :** | **End :**  |
| **Title of Research Project** | : |  |  |
|  | : |  |  |
| **Grant’s Code (if any)** | : |  |  |
| **Source of Funding (if any)** |  |  |  |
| **Title of Invention** | : |  |  |

**PART B**

**REQUEST FOR: SEARCH & FILING**

*(Tick (√) only ONE)*

 Patent Utility Innovation Plant Variety

**PART C**

1. Which of the following best describes your invention? *(Tick all those appropriate)*

**New product Improvement in quality**

**New process Improvement in performances**

**New solution to existing problems Reduction to cost**

**Improvement in Product Improvement in process**

 **Others:\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**

1. Which of the following best describes the novelty of your invention?

 **New only in Malaysia New worldwide**

1. Is your invention similar to an existing product/process? If yes, state in what way your invention is an improvement over the existing product/process.

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1. What kind of solution that your invention/product gives to the existing technology?

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1. Is your invention/product scalable for mass production? If no, give reasons. If yes, state the limitations, if any.

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1. Is the process involved repeatable, such that any party may produce it (upon licensing)? If no, please state why? Identify weak points (if any) here?

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1. Exposure: has your invention/product ever been disclosed?

|  |  |  |
| --- | --- | --- |
|  | **Date** | **Venue** |
| **Exhibition** |  |  |
| **Publication/ Journal** |  |  |
| **Public (Mass media)** |  |  |
| **Seminar/Conference** |  |  |
| **Industry** |  |  |
| **Others** |  |  |

1. **Field of Invention** (This invention relates primarily to)
2. **Background art**

(In this section the inventor should described the technical problem of the invention technology, any prior art related to the invention, and the advantages of the invention)

1. **Summary of the invention** (This section is for the inventor to summarize the technology)
2. **Description of the invention** (In this section is the write of description of the picture attached)
3. **Detailed description of the invention** (In this section a full disclosure of the Invention)
4. **Picture** (Picture can be labelled as number or the name of the part)

**PART D**

**I hereby disclosing the research information needed for further process of Intellectual Property protection.**

Applicant’s Signature: Date:

Official Stamp:

**PART E**  *[For PPIP use only]*

Ref: **IP2/**

Date of receipt:

Comments:

Appointed Agent: